# Final Product/Process Change Notification

Document #:FPCN25224X
Issue Date:05 Jul 2023

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|---|---|
| **Title of Change:** | Qualification of onsemi Aizu Japan as wafer Fab for ONC25BCD Technology for select products in NCS20071 family |
| **Proposed First Ship date:** | 12 Oct 2023 or earlier if approved by customer |
| **Contact Information:** | Contact your local onsemi Sales Office or Adrian.Croitoru@onsemi.com |
| **PCN Samples Contact:** | Contact your local onsemi Sales Office.<br>Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.<br>Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements. |
| **Additional Reliability Data:** | Contact your local onsemi Sales Office or Vladislav.Hrachovec@onsemi.com |
| **Type of Notification:** | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change.<br>onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com |
| **Marking of Parts/ Traceability of Change:** | Custom source information will be updated on product label. Product traceability will be identified by encoded date code. |
| **Change Category:** | Wafer Fab Change |
| **Change Sub-Category(s):** | Manufacturing Site Addition |

**Sites Affected:**

| **onsemi Sites** | **External Foundry/Subcon Sites** |
|---|---|
| onsemi Aizu, Japan | None |

**Description and Purpose:**

onsemi would like to inform its customers of qualification of an additional wafer fabrication facility for ONC25 technology at onsemi Aizu, Japan for the devices listed in this FPCN. All products listed here will be dual sourced from onsemi Gresham and onsemi Aizu.

There is no change to the orderable part number.

There is no product marking change as a result of this notification.

No changes to part specification or datasheet are anticipated.

| NCS20071 FAMILY – TSOP5 and SOT553 packages | From | To |
|---|---|---|
| Wafer Fab | onsemi, Gresham, Oregon (US) | onsemi, Gresham, Oregon (US)<br>onsemi, Aizu (Japan) |

## Reliability Data Summary:

**QV DEVICE NAME: NCS20072DR2G**
**RMS: O86311**
**PACKAGE: SOIC-8**

| Test | Specification | Condition | Interval | Results |
|---|---|---|---|---|
| High Temperature Operating Life | JESD22-A108 | Ta=125°C, 100 % max rated Vcc | 1008 hrs | 0/77 |
| High Temperature Storage Life | JESD22-A103 | Ta= 150°C | 1008 hrs | 0/77 |
| Early Life Failure Rate | JESD22-A108 | Ta=125°C, 100 % max rated Vcc | 48 hrs | 0/800 |
| Preconditioning | J-STD-020 JESD-A113 | MSL 1 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only | | 0/all |
| Temperature Cycling | JESD22-A104 | Ta= -55°C to +150°C | 1000 cyc | 0/77 |
| Highly Accelerated Stress Test | JESD22-A110 | 130°C, 85% RH, 18.8psig, bias | 96 hrs | 0/77 |
| Unbiased Highly Accelerated Stress Test | JESD22-A118 | 130°C, 85% RH, 18.8psig, unbiased | 96 hrs | 0/77 |

## Electrical Characteristics Summary:

Electrical characteristics are not impacted.

## List of Affected Parts:

***Note:*** *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal****.*

| Part Number | Qualification Vehicle |
|---|---|
| NCS20071XV53T2G | NCS20072DR2G |
| NCS20071SN2T1G | NCS20072DR2G |